

HX318C10FBK2/16

16GB (8GB 1G x 64-Bit x 2 pcs.)
 DDR3-1866 CL10 240-Pin DIMM Kit



SPECIFICATIONS

CL(IDD)	10 cycles
Row Cycle Time (tRCmin)	44.75ns (min.)
Refresh to Active/Refresh Command Time (tRFCmin)	260ns (min.)
Row Active Time (tRASmin)	32.125ns (min.)
Maximum Operating Power	TBD W* (per module)
UL Rating	94 V - 0
Operating Temperature	0° C to 85° C
Storage Temperature	-55° C to +100° C

*Power will vary depending on the SDRAM used.

DESCRIPTION

HyperX HX318C10FBK2/16 is a kit of two 1G x 64-bit (8GB) DDR3-1866 CL10 SDRAM (Synchronous DRAM) 2Rx8 memory modules, based on sixteen 512M x 8-bit DDR3 FBGA components per module. Total kit capacity is 16GB. Each module kit has been tested to run at DDR3-1866 at a low latency timing of 10-11-10 at 1.5V. Additional timing parameters are shown in the PnP Timing Parameters section below. The JEDEC standard electrical and mechanical specifications are as follows:

Note: The PnP feature offers a range of speed and timing options to support the widest variety of processors and chipsets. Your maximum speed will be determined by your BIOS.

PnP JEDEC TIMING PARAMETERS:

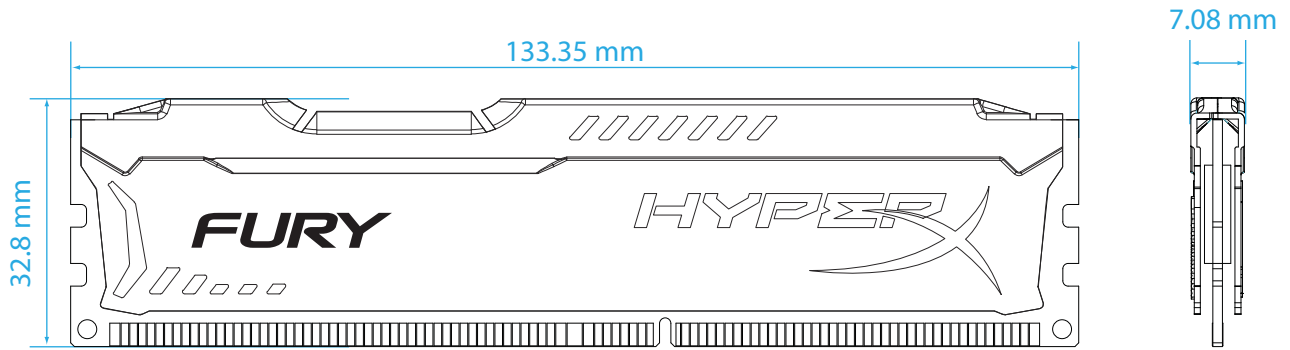
- DDR3-1866 CL10-11-10 @1.5V
- DDR3-1600 CL9-10-9 @1.5V
- DDR3-1333 CL8-9-8 @1.5V

FEATURES

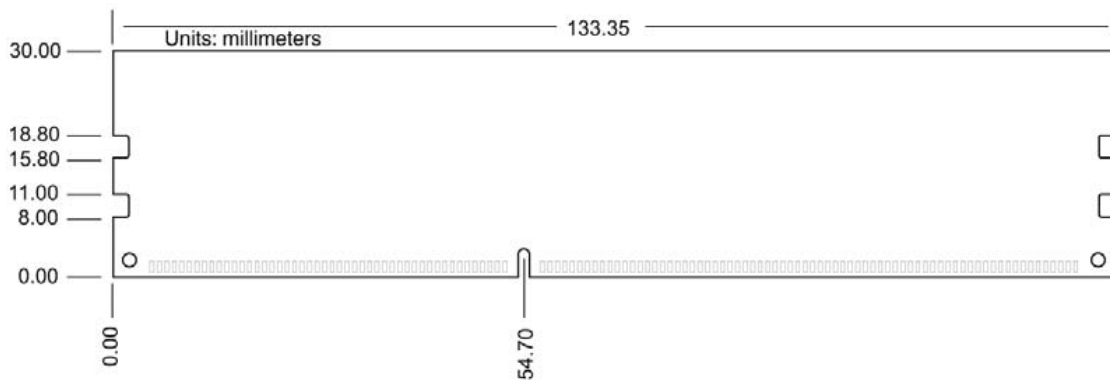
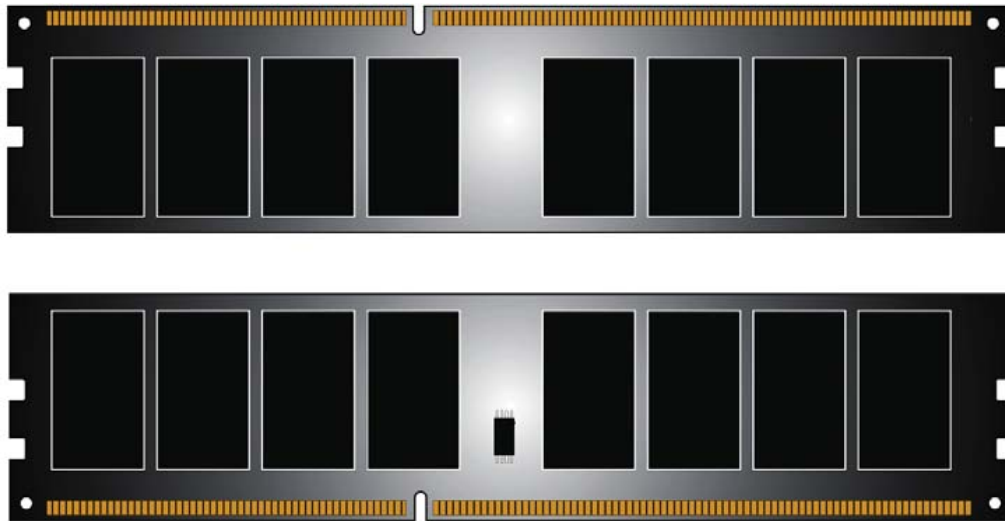
- JEDEC standard 1.5V (1.425V ~1.575V) Power Supply
- VDDQ = 1.5V (1.425V ~ 1.575V)
- 933MHz fCK for 1866Mb/sec/pin
- 8 independent internal bank
- Programmable CAS Latency: 13, 11, 10, 9, 8, 7, 6
- Programmable Additive Latency: 0, CL - 2, or CL - 1 clock
- 8-bit pre-fetch
- Burst Length: 8 (Interleave without any limit, sequential with starting address "000" only), 4 with tCCD = 4 which does not allow seamless read or write [either on the fly using A12 or MRS]
- Bi-directional Differential Data Strobe
- Internal(self) calibration : Internal self calibration through ZQ pin (RZQ : 240 ohm ± 1%)
- On Die Termination using ODT pin
- Average Refresh Period 7.8us at lower than TCASE 85°C, 3.9us at 85°C < TCASE ≤ 95°C
- Asynchronous Reset
- Height 1.291" (32.80mm) w/heatsink, double sided component

Continued >>

MODULE WITH HEAT SPREADER



MODULE DIMENSIONS



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